



Material Content Data Sheet



Sales Product Name		BFN 38 H6327		Issued		19. July 2018		
MA#		MA001211996						
Package		PG-SOT223-4-24		Weight*		107.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.013	0.01		122	
	non noble metal	tin	7440-31-5	0.003	0.00		32	
	inorganic material	silicon	7440-21-3	0.160	0.15	0.16	1492	1646
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		80	
	non noble metal	titanium	7440-32-6	0.043	0.04		398	
	non noble metal	chromium	7440-47-3	0.128	0.12		1194	
	non noble metal	copper	7440-50-8	42.459	39.63	39.80	396298	397970
wire	non noble metal	copper	7440-50-8	0.020	0.02	0.02	190	190
encapsulation	organic material	carbon black	1333-86-4	0.623	0.58		5819	
	plastics	epoxy resin	-	9.352	8.73		87287	
	inorganic material	silicondioxide	60676-86-0	52.370	48.88	58.19	488807	581913
leadfinish	non noble metal	tin	7440-31-5	1.464	1.37	1.37	13664	13664
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4617	4617
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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